



HIGH DIODE

MURS405 THRU MURS460

SMC Plastic-Encapsulate Diodes

Super Fast Recovery Rectifier Diode

Features

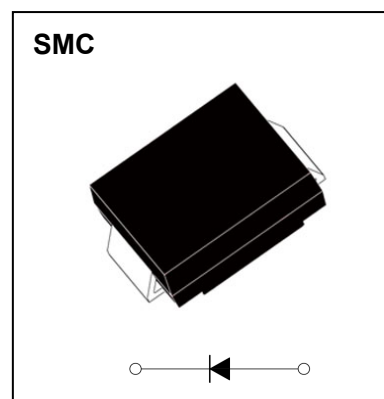
- I_O 4A
- V_{RRM} 50V-600V
- High surge current capability
- Glass passivated chip
- Polarity: Color band denotes cathode

Applications

- Rectifier

Marking

- MURS4XX
- XX: From 05 To 60



Limiting Values (Absolute Maximum Rating)

Item	Symbol	Unit	Test Conditions	MURS40							
				05	10	15	20	30	40	50	60
Repetitive Peak Reverse Voltage	V_{RRM}	V		50	100	150	200	300	400	500	600
Maximum RMS Voltage	V_{RMS}	V		35	70	105	140	210	280	350	420
Average Forward Current	$I_{F(AV)}$	A	60Hz Half-sine wave, Resistance load, $T_L=100^\circ\text{C}$	4.0							
Surge(Non-repetitive)Forward Current	I_{FSM}	A	60Hz Half-sine wave, 1 cycle, $T_a=25^\circ\text{C}$	125							
Junction Temperature	T_J	$^\circ\text{C}$		-55~+150							
Storage Temperature	T_{STG}	$^\circ\text{C}$		-55 ~ +150							

Electrical Characteristics ($T = 25^\circ\text{C}$ Unless otherwise specified)

Item	Symbol	Unit	Test Condition	MURS40								
				05	10	15	20	30	40	50	60	
Peak Forward Voltage	V_F	V	$I_F=4.0\text{A}$	0.89				1.28				
Maximum reverse recovery time	t_{rr}	ns	$I_F=0.5\text{A}, I_R=1.0\text{A}, I_{rr}=0.25\text{A}$	35								
Peak Reverse Current	I_{RRM1}	μA	$V_{RM}=V_{RRM}$	$T_a=25^\circ\text{C}$				10				
	I_{RRM2}			$T_a=100^\circ\text{C}$				100				
Thermal Resistance(Typical)	$R_{\theta J-A}$	$^\circ\text{C/W}$	Between junction and ambient		20 ¹⁾							
	$R_{\theta J-L}$		Between junction and terminal		12 ¹⁾							

Notes:

Thermal resistance from junction to ambient and from junction to lead mounted on P.C.B. with 0.3" x 0.3" (8.0 mm x 8.0 mm) copper pad areas

Typical Characteristics

FIG. 1- FORWARD CURRENT DERATING CURVE

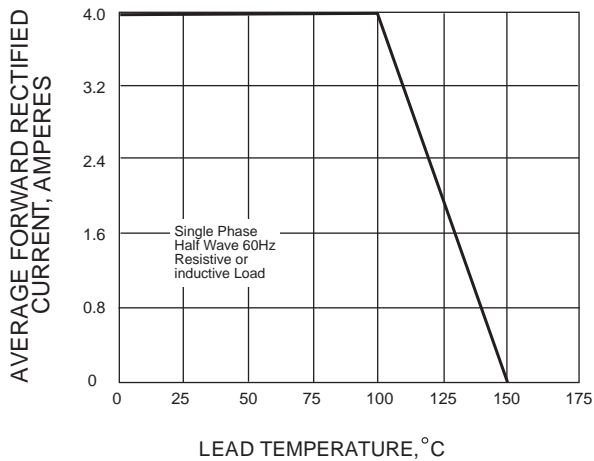


FIG. 2-MAXIMUM NON-REPETITIVE PEAK FORWARD SURGE CURRENT

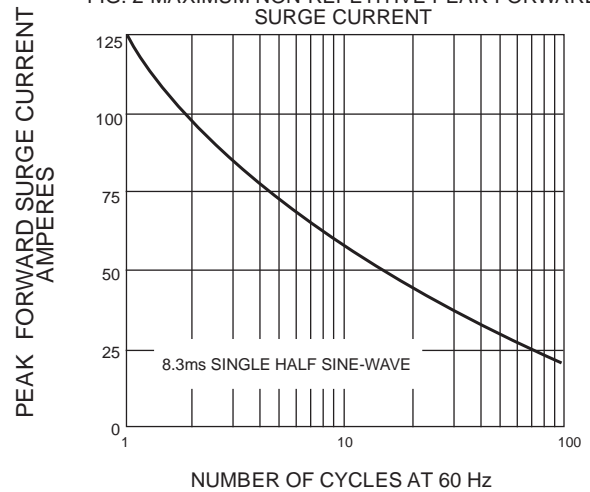


FIG. 3-TYPICAL INSTANTANEOUS FORWARD CHARACTERISTICS

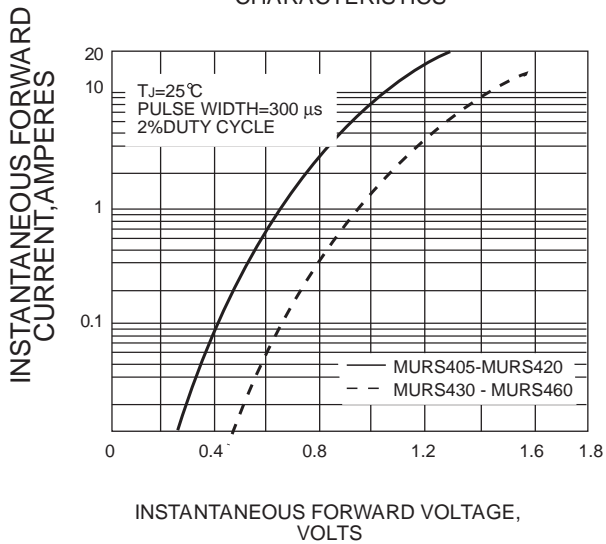
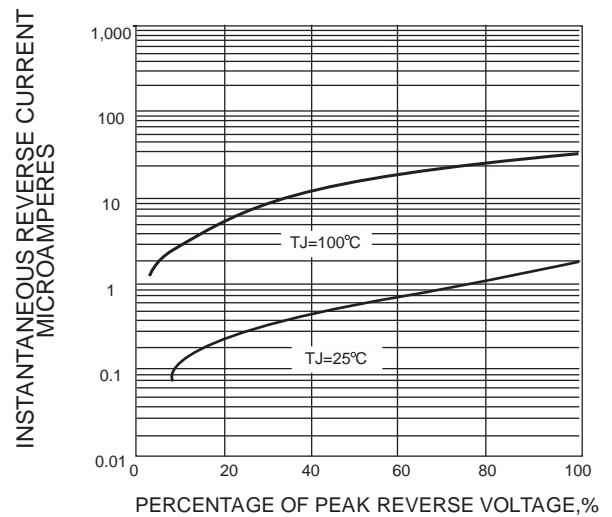
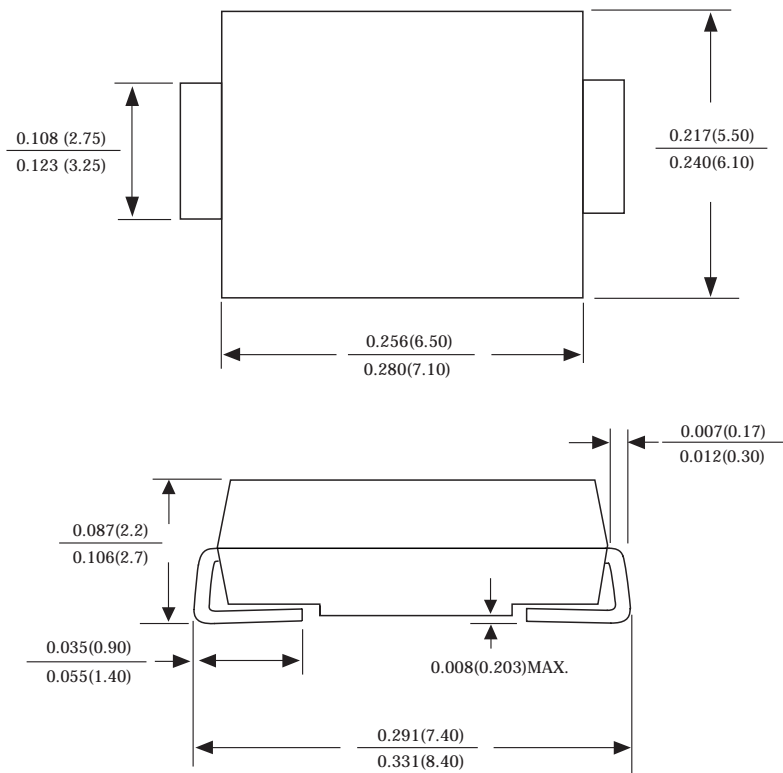


FIG. 4-TYPICAL REVERSE CHARACTERISTICS

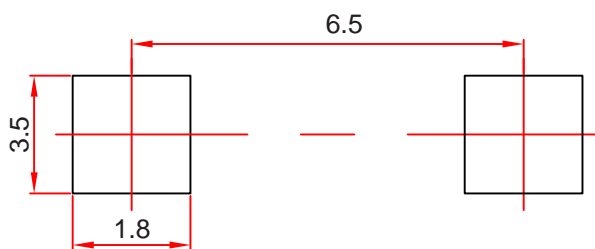


SMC Package Outline Dimensions



Dimensions in inches and (millimeters)

SMC Suggested Pad Layout



Note:

1. Controlling dimension: in millimeters.
2. General tolerance: ± 0.05 mm.
3. The pad layout is for reference purposes only.

NOTICE

JSHD reserve the right to make modifications, enhancements, improvements, corrections or other changes without further notice to any product herein. JSHD does not assume any liability arising out of the application or use of any product described herein.

Reel Taping Specifications For Surface Mount Devices–SMC

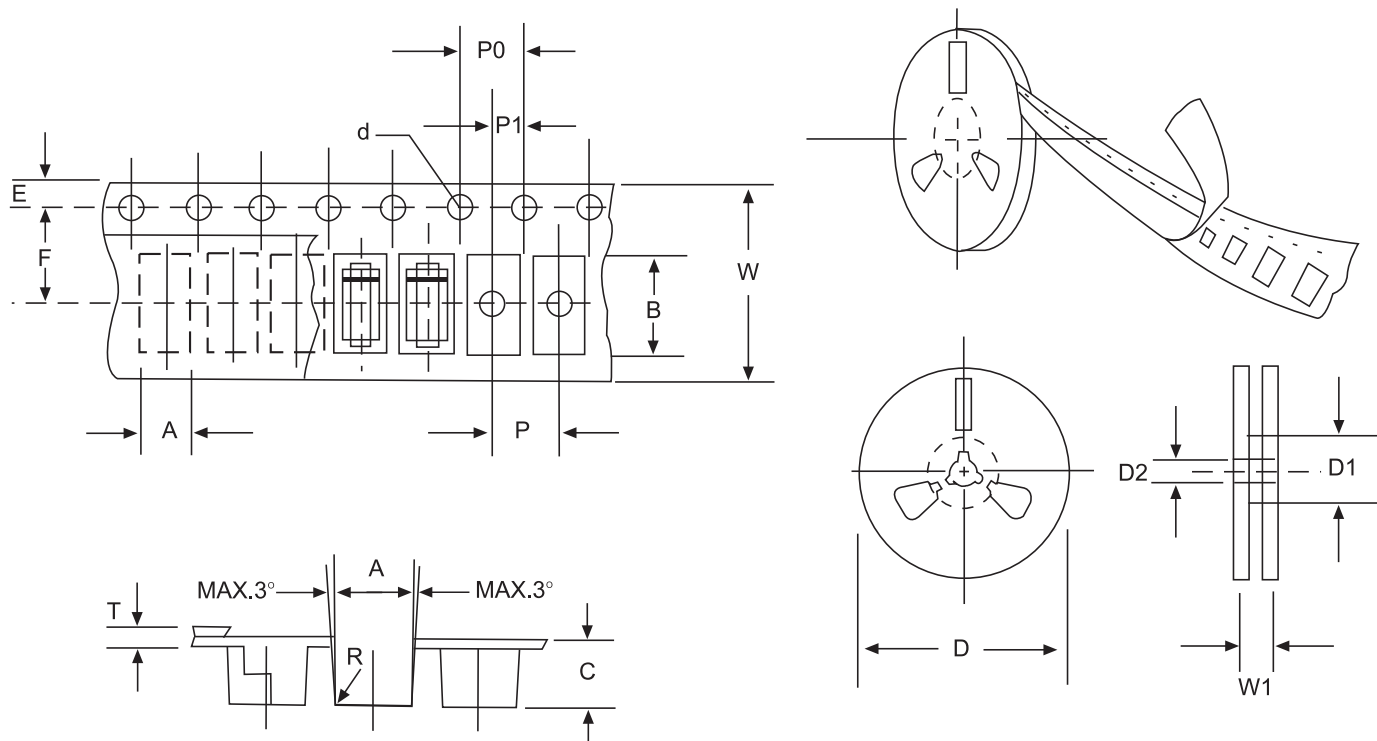


FIG:CONFIGURATION OF AXIAL TAPING

ITEM	SYMBOL	SMC mm(inch)
Carrier width	A	6.05±0.1(0.238±0.004)
Carrier length	B	8.31±0.1(0.327±0.004)
Carrier depth	C	2.50±0.1(0.100±0.004)
Sprocket hole	d	1.5±0.1(0.059±0.004)
Reel outside diameter	D	330/281/178±2(13/11/7±0.079)
Reel inner diameter	D1	8.0±0.2(0.315±0.008)
Feed hole diameter	D2	13±0.5(0.512±0.020)
Sprocket hole position	E	1.5±0.1(0.059±0.004)
Punch hole position	F	7.65±0.05(0.301±0.002)
Punch hole pitch	P	8.0±0.1(0.315±0.004)
Sprocket hole pitch	P0	4.0±0.1(0.157±0.004)
Embossment center	P1	2.0±0.1(0.079±0.004)
Total tape thickness	T	0.3±0.1(0.012±0.004)
Tape width	W	16.0±0.2(0.630±0.008)
Reel width	W1	24.0±2.0(0.945±0.079)

NOTE: Devices are packed in accordance with EIA standard RS-481-A and specification given above.